

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD50N10S3L-16	**Issued**	11. May 2021
MA#	MA001659164		
Package	PG-TO252-3-11	**Weight***	373.45 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.497	1.20	1.20	12042	12042
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.57	57.65	575760	576510
wire	non noble metal	aluminium	7429-90-5	4.661	1.25	1.25	12481	12481
encapsulation	inorganic material	zincoxide	1314-13-2	1.219	0.33		3265	
	miscellaneous	miscellaneous	-	6.096	1.63		16324	
	plastics	epoxy resin	-	18.289	4.90		48973	
	inorganic material	silicondioxide	60676-86-0	96.321	25.79	32.65	257922	326484
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10015	10015
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.081	0.02		216	
	noble metal	silver	7440-22-4	0.101	0.03		270	
	non noble metal	lead	7439-92-1	3.854	1.03	1.08	10320	10806
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51352	51418
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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